

IN THE SPECIFICATION

Before the section heading on page 1, at line 7, please insert the following section heading and paragraph:

CROSS REFERENCE

This application is a national stage of PCT/JP04/17534, filed on June 1, 2004, and claims benefit under 35 U.S.C. § 119 from Japanese Patent Application No. 2003-167818, filed on June 12, 2003, and Japanese Patent Application No. 2003-275407, filed on July 16, 2003.

Please amend the paragraph at page 45, lines 8-15, as follows:

Moreover, any of the conducting path forming portions 11, which is formed on a peripheral edge portion in the anisotropic conductive ~~portion~~ film 10A, is set to be an ineffective conducting path forming portion 13 which is not electrically connected to the electrode to be the connecting object. The effective conducting path forming portion 12 is disposed in accordance with a pattern corresponding to the pattern of the electrode to be the connecting object.

Please amend the paragraph beginning at page 67, the last line through page 68, line 5, as follows:

The anisotropic conductive connector device 10 according to the second example can be manufactured in the same manner as the anisotropic conductive connector device according to the first example except that a sheet-like connector 20 shown in Fig. [[24]] 25 is used in place of the sheet-like connector 20 shown in Fig. 11.

Please amend the paragraph at page 75, lines 4-13, as follows:

According to such a manufacturing method, in a state in which the sheet-like connector 20 is disposed on a molding material layer [[10B]] 19 for forming the anisotropic conductive film 10A, a material constituting the anisotropic conductive film is cured in a permeation condition into the void of the insulating sheet 21. Consequently, the molding material layer [[10B]] 19 is subjected to a curing treatment. Thus, it is possible to advantageously and reliably manufacture the anisotropic conductive connector device 10 in which the sheet-like connector 20 is integrated on the anisotropic conductive film 10A.

Please amend the paragraph at page 76, lines 18-24, as follows:

In this state, the circuit device 1 is pressed in such a direction as to approach a circuit board [[5]] 40 for an inspection, for example. Consequently, each of the effective conducting path forming portions 12 in the anisotropic conductive connector device 10 is interposed by pressure between the electrode structure 22 in the sheet-like connector 20 and the electrode 41 for an inspection.

Please amend the paragraph at page 86, lines 1-6, as follows:

The laminating material having the opening portion thus obtained was subjected to a nonelectrolytic plating treatment by using a copper plating solution (OKUNO CHEMICAL INDUSTRIES CO., LTD. : BVF) so that a laminating material having the electrode structure (22) formed in the opening portion shown in Fig. [[33]] 32 was obtained.

Please amend the paragraph beginning at page 91, line 21, through page 92, line 6, as follows:

The circuit device 3 for a test has 72 solder ball electrodes [[4]] 2 (material: 64 solder) in total, each of which has a diameter of 0.4 mm and a height of 0.3 mm. Two electrode

groups are formed, each of which has 36 solder ball electrodes [[4]] 2 provided therein. In each of the electrode groups, there are formed two lines in total, each of which has 18 solder ball electrodes 2 arranged straight at a pitch of 0.8 mm. Two of the solder ball electrodes are electrically connected to each other through a wiring 8 in the circuit device 3. The total number of the wirings in the circuit device 3 is 36.

Please amend the paragraph beginning at page 92, line 22, through page 93, line 7, as follows:

Then, a DC current of 10 mA was always applied by a DC power supply 115 and a constant current control device 116 between external terminals (not shown) of the circuit board 5 for an inspection, which are electrically connected to each other through the anisotropic conductive connector 10, the circuit device 3 for a test, and the electrode [[2]] 6 for an inspection and a wiring thereof (not shown) of the circuit board 5 for an inspection. In this state, a voltage between the external terminals of the circuit board 5 for an inspection during the pressurization was measured by means of a voltmeter 110.